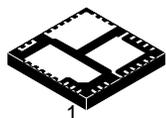


# MECHANICAL CASE OUTLINE

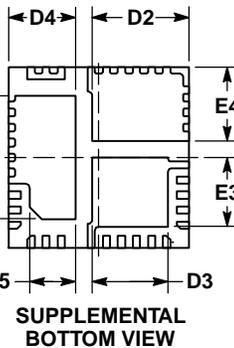
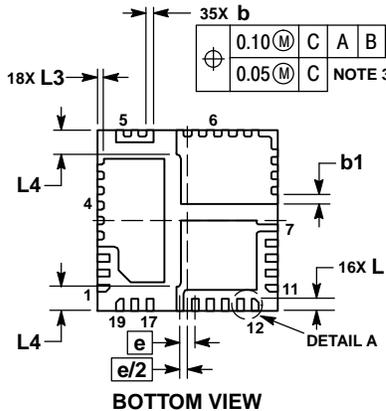
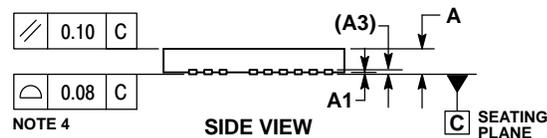
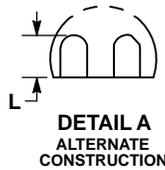
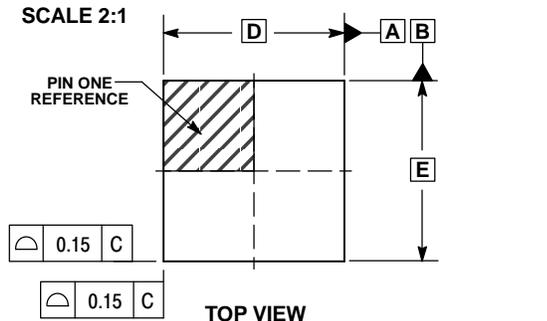
## PACKAGE DIMENSIONS

ON Semiconductor®



**QFN19 6x6, 0.5P**  
CASE 485FL  
ISSUE A

DATE 27 SEP 2017

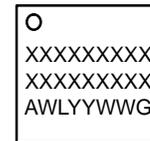


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSIONS: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PADS AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.80	1.00
A1	---	0.05
A3	0.20	REF
b	0.18	0.30
b1	0.26	0.38
D	6.00	BSC
D2	3.12	3.32
D3	2.47	2.57
D4	2.13	2.33
D5	1.47	1.58
E	6.00	BSC
E2	4.04	4.14
E3	2.25	2.35
E4	2.35	2.55
e	0.50	BSC
L	0.30	0.50
L3	0.10	0.30
L4	0.70	0.90

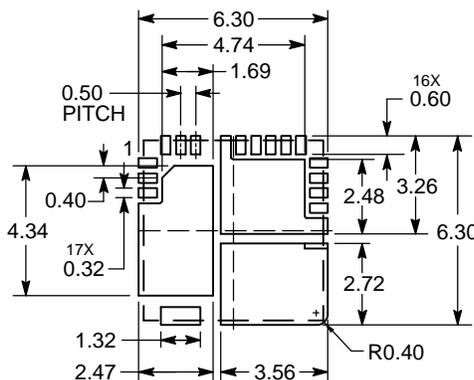
**GENERIC MARKING DIAGRAM\***



- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

**RECOMMENDED SOLDERING FOOTPRINT\***



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>STATUS:</b>	<b>ON SEMICONDUCTOR STANDARD</b>	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	<b>QFN19 6x6, 0.5P</b>	<b>PAGE 1 OF 2</b>

